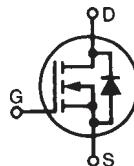


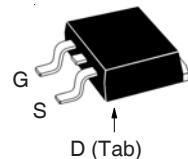
**Trench™ HiperFET™
Power MOSFET**
**IXFA130N10T
IXFP130N10T**

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode

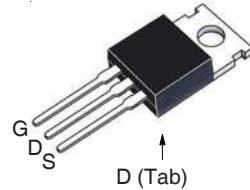


V_{DSS} = 100V
 I_{D25} = 130A
 $R_{DS(on)}$ ≤ 9.1mΩ

TO-263
(IXFA)



TO-220
(IXFP)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_j = 25^\circ\text{C}$ to 175°C	100	V
V_{DGR}	$T_j = 25^\circ\text{C}$ to 175°C , $R_{GS} = 1\text{M}\Omega$	100	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_c = 25^\circ\text{C}$	130	A
I_{LRMS}	Lead Current Limit, RMS	120	A
I_{DM}	$T_c = 25^\circ\text{C}$, Pulse Width Limited by T_{JM}	350	A
I_A	$T_c = 25^\circ\text{C}$	65	A
E_{AS}	$T_c = 25^\circ\text{C}$	750	mJ
P_D	$T_c = 25^\circ\text{C}$	360	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_c	Mounting Force (TO-263)	10..65 / 2.2..14.6	N/lb
M_d	Mounting Torque (TO-220)	1.13 / 10	Nm/lb.in
Weight	TO-263	2.5	g
	TO-220	3.0	g

Symbol	Test Conditions ($T_j = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1\text{mA}$	2.5		V
I_{GSS}	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$		± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0\text{V}$ $T_j = 150^\circ\text{C}$		10 500	μA
$R_{DS(on)}$	$V_{GS} = 10\text{V}$, $I_D = 25\text{A}$, Notes 1, 2		9.1	mΩ

Features

- Ultra-Low On Resistance
- Avalanche Rated
- Low Package Inductance
 - Easy to Drive and to Protect
- 175°C Operating Temperature
- Fast Intrinsic Diode

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- Automotive
 - Motor Drives
 - 42V Power Bus
 - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary Switch for 24V and 48V Systems
- Distributed Power Architectures and VRMs
- Electronic Valve Train Systems
- High Current Switching Applications
- High Voltage Synchronous Rectifier

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	55	93	S
C_{iss}		5080		pF
C_{oss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	630		pF
C_{rss}		95		pF
$t_{d(on)}$		30		ns
t_r		47		ns
$t_{d(off)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 25\text{A}$	44		ns
t_f	$R_G = 5\Omega$ (External)	28		ns
$Q_{g(on)}$		104		nC
Q_{gs}	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 25\text{A}$	30		nC
Q_{gd}		29		nC
R_{thJC}			0.42	$^\circ\text{C}/\text{W}$
R_{thCH}	TO-220	0.50		$^\circ\text{C}/\text{W}$

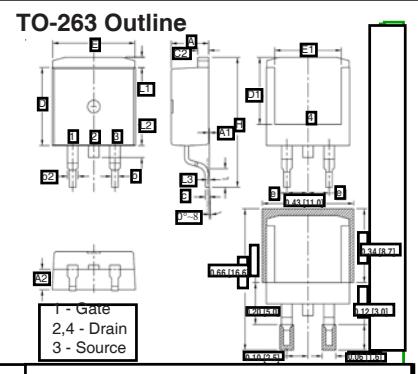
Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	$V_{GS} = 0\text{V}$		130	A
I_{sm}	Repetitive, Pulse Width Limited by T_{JM}		350	A
V_{SD}	$I_F = 25\text{A}$, $V_{GS} = 0\text{V}$, Note 1		1.0	V
t_{rr}		67		ns
I_{RM}	$I_F = 65\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$	4.7		A
Q_{rr}	$V_R = 0.5 \cdot V_{DSS}$, $V_{GS} = 0\text{V}$	160		nC

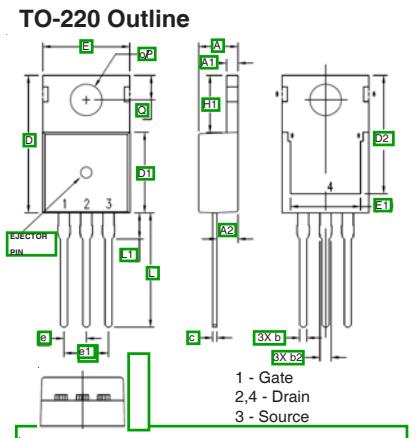
- Notes:
1. Pulse test, $t \leq 300 \mu\text{s}$; duty cycle, $d \leq 2\%$.
 2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5 mm or less from the package body.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.



SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.060	1.18	1.52
C	.018	.024	0.45	0.60
C2	.049	.060	1.25	1.52
D	.340	.370	8.63	9.40
D1	.300	.327	7.62	8.30
E	.380	.410	9.65	10.41
E1	.270	.330	6.86	8.38
e	.100	BSC	2.54	BSC
H	.580	.620	14.73	15.75
L	.075	.105	1.91	2.67
L1	.039	.060	1.00	1.52
L2	—	.070	—	1.77
L3	.010	BSC	0.254	BSC



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100	BSC	2.54	BSC
e1	.200	BSC	5.08	BSC
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
ØP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

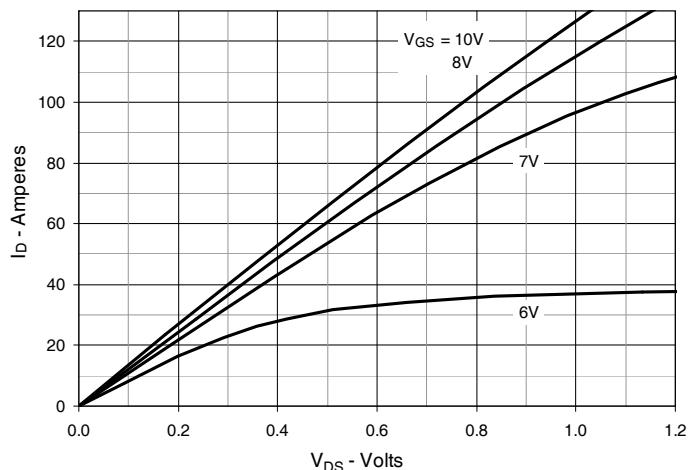
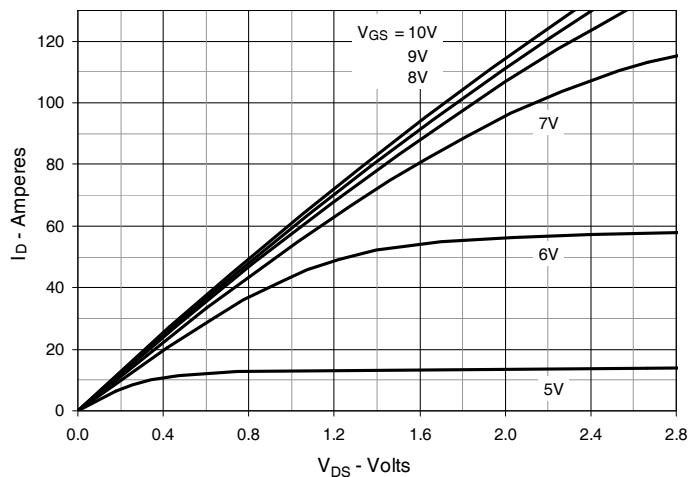
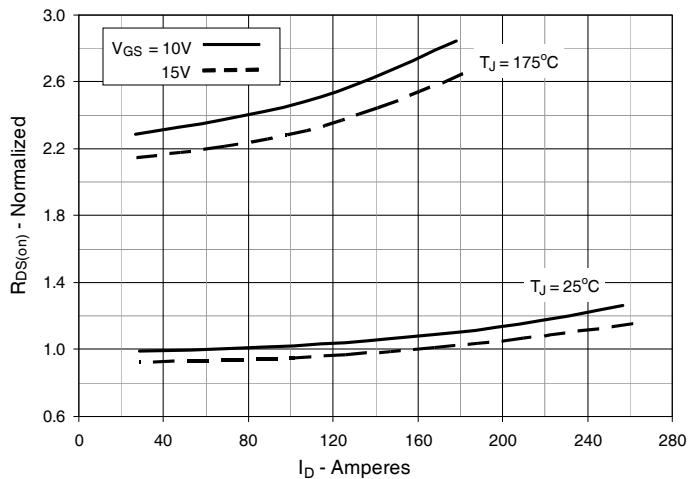
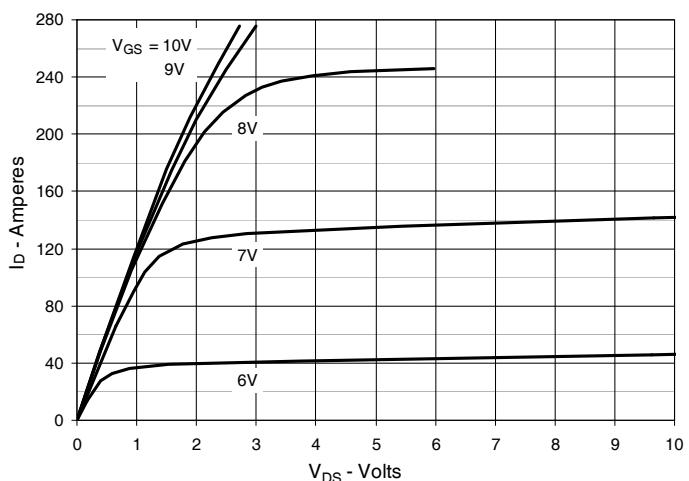
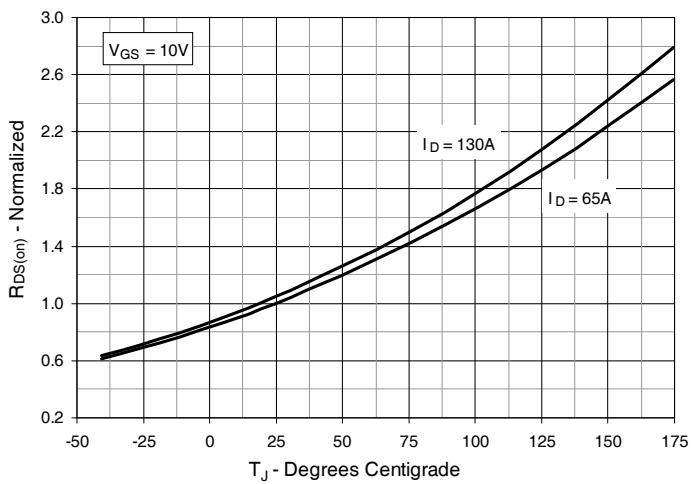
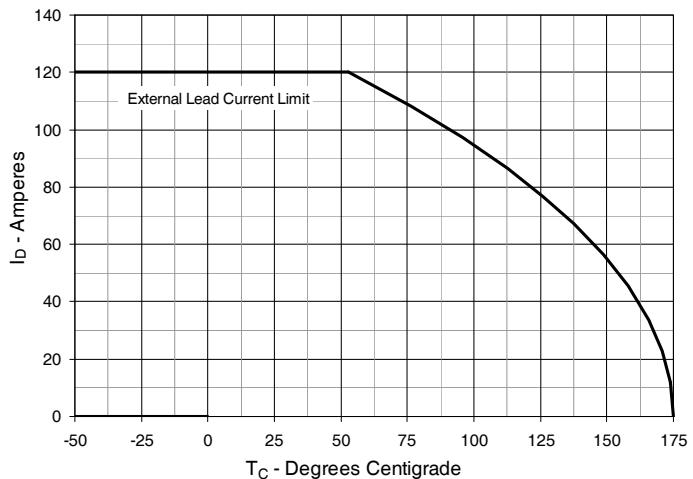
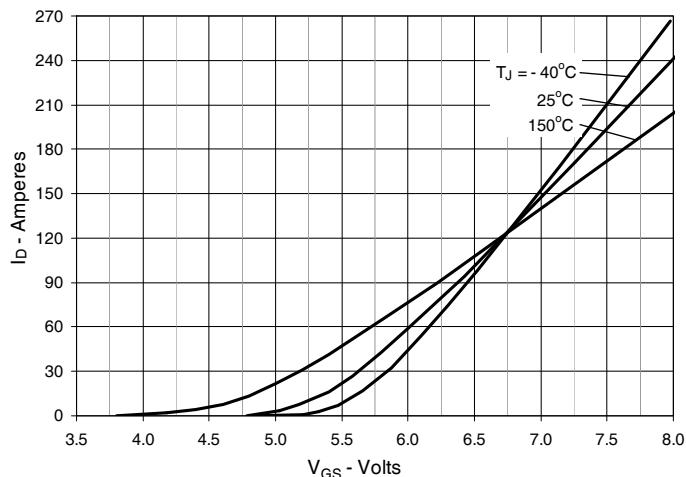
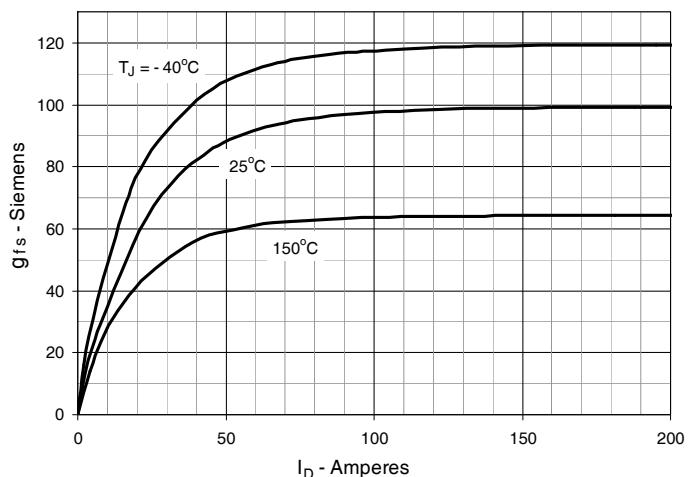
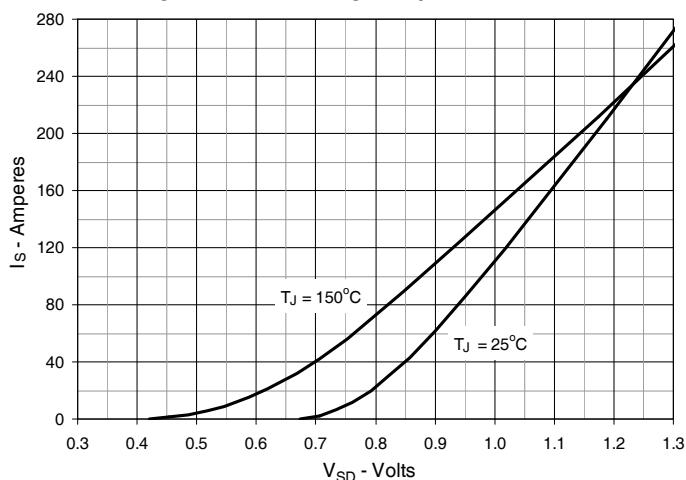
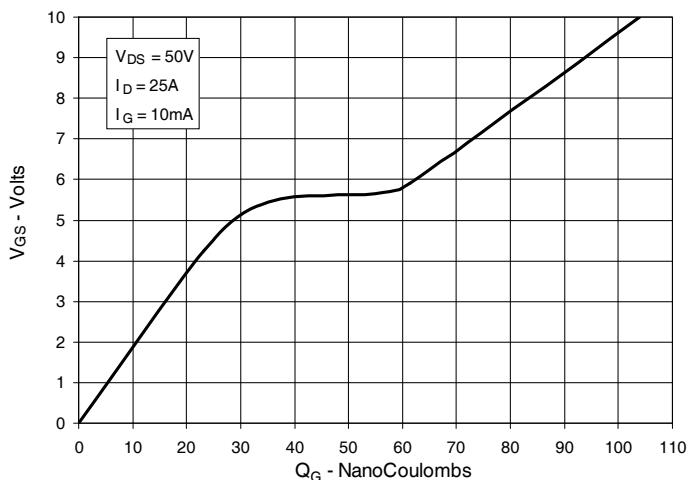
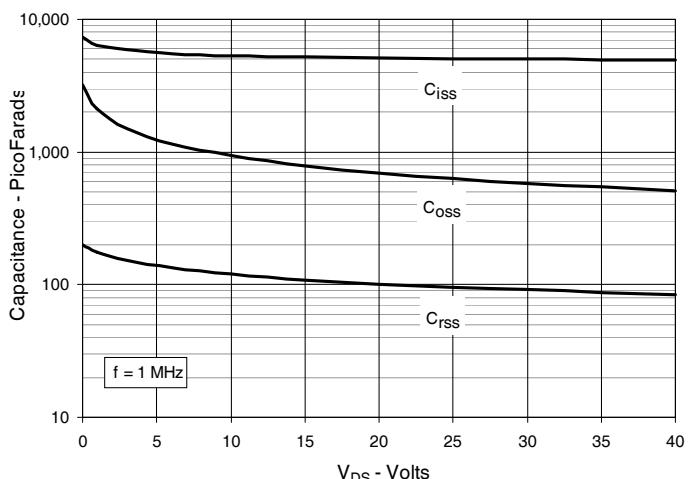
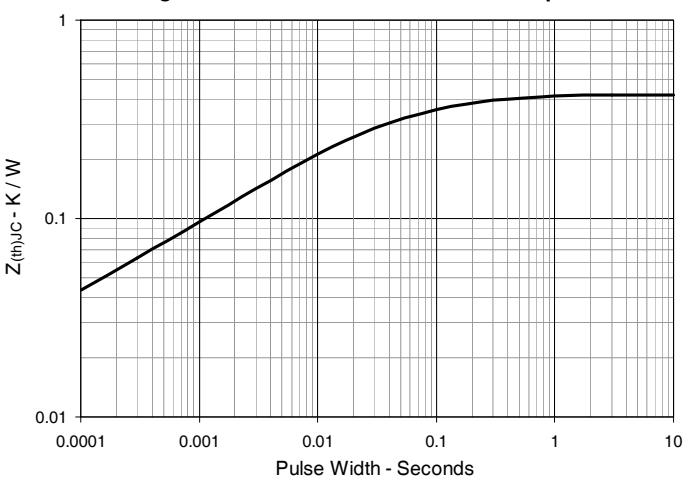
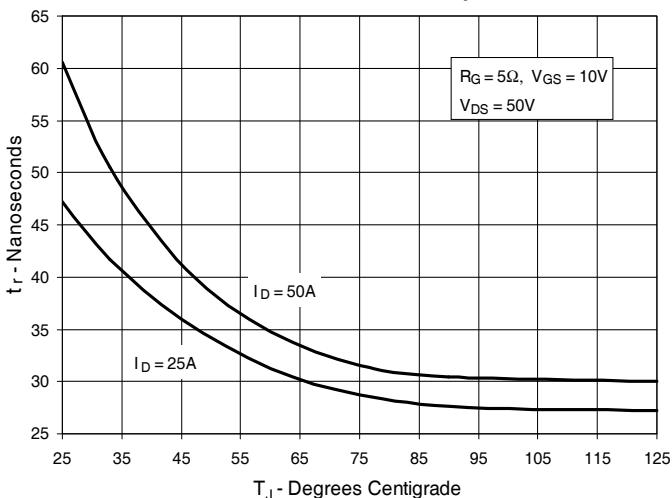
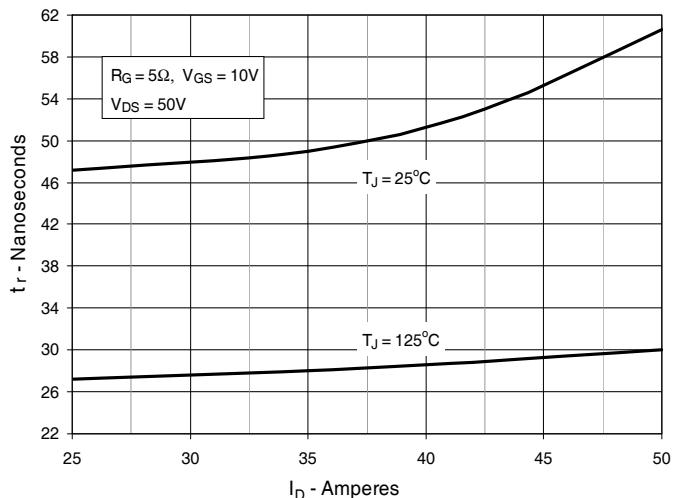
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 65\text{A}$ Value vs. Drain Current

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 65\text{A}$ Value vs. Junction Temperature

Fig. 6. Drain Current vs. Case Temperature


Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Forward Voltage Drop of Intrinsic Diode

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Impedance


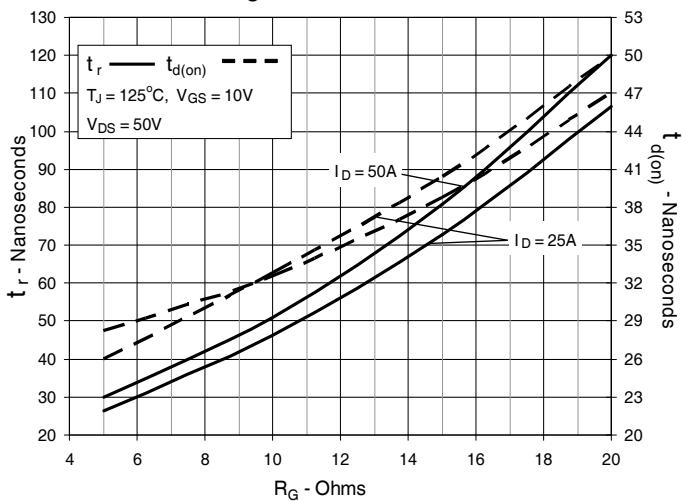
**Fig. 13. Resistive Turn-on
Rise Time vs. Junction Temperature**



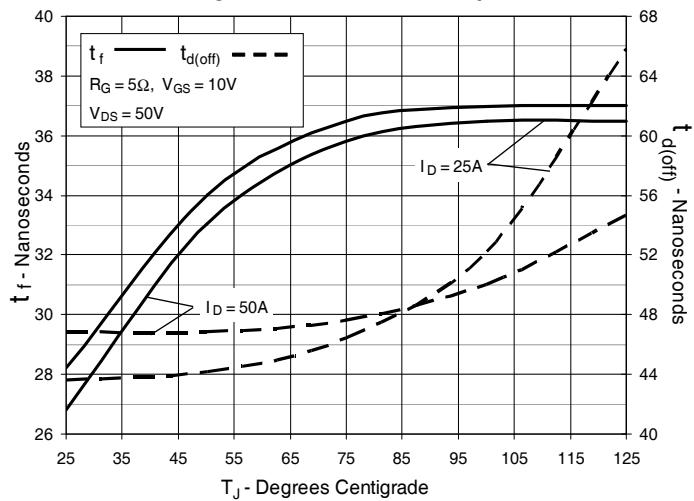
**Fig. 14. Resistive Turn-on
Rise Time vs. Drain Current**



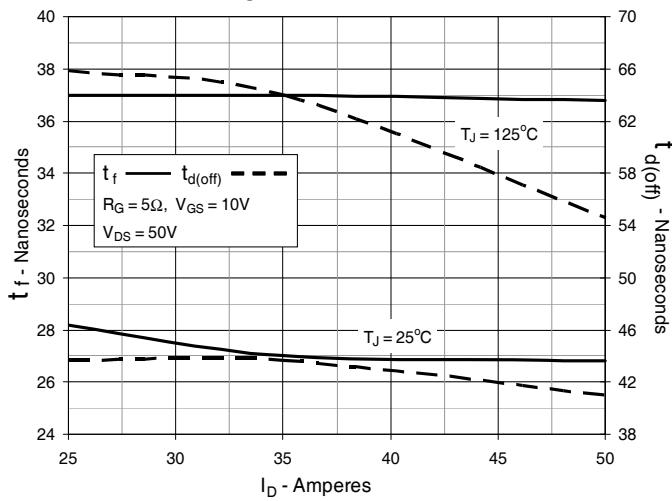
**Fig. 15. Resistive Turn-on
Switching Times vs. Gate Resistance**



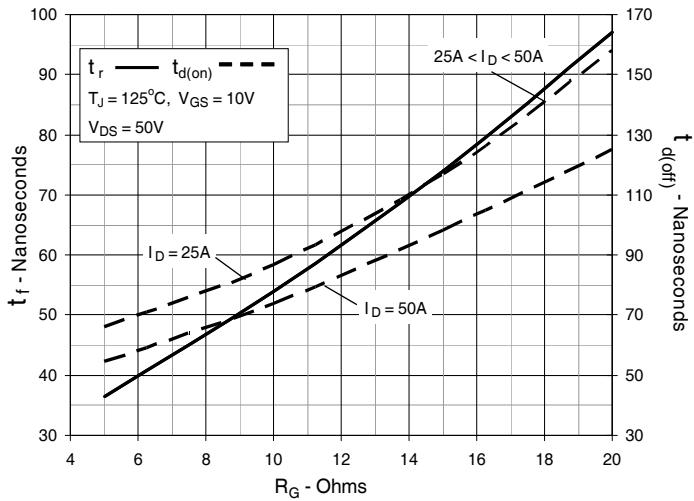
**Fig. 16. Resistive Turn-off
Switching Times vs. Junction Temperature**



**Fig. 17. Resistive Turn-off
Switching Times vs. Drain Current**



**Fig. 18. Resistive Turn-off
Switching Times vs. Gate Resistance**





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